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(21) International Application Number: PCT/US99/21409 (22) International Filing Date: 16 September 1999 (16.09.99) (30) Priority Data: 09/154,417 16 September 1998 (16.09.98) US (63) Related by Continuation (CON) or Continuation-in-Part (CIP) to Earlier Application US 09/154,417 (CON) Filed on 16 September 1998 (16.09.98) (71) Applicant (for all designated States except US): KULICKE & SOFFA INVESTMENTS, INC. [US/US]; 2101 Blair Mill Road, Willow Grove, PA 19090 (US). (72) Inventor; and (75) Inventor/Applicant (for US only): SEUNTJENS, Jeffrey, M. [US/SG]; 73 Nim Road, #07-03, Singapore 807854 (SG). (74) Agents: BUTCH, Peter, J. III et al.; Synnestvedt & Lechner LLP, 2600 Aramark Tower, Philadelphia, PA 19107 (US).		(81) Designated States: CN, JP, KR, SG, US, European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published <i>With international search report. Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i>
(54) Title: COMPOSITE WIRE WITH NOBLE METAL CLADDING (57) Abstract Composite wires characterized by a noble metal annulus welded to a wire core comprising an electrically-conductive, non-noble metal. Methods of forming the composite wire and semiconductor packaging having at least one lead bonded to the composite wire are also disclosed.		